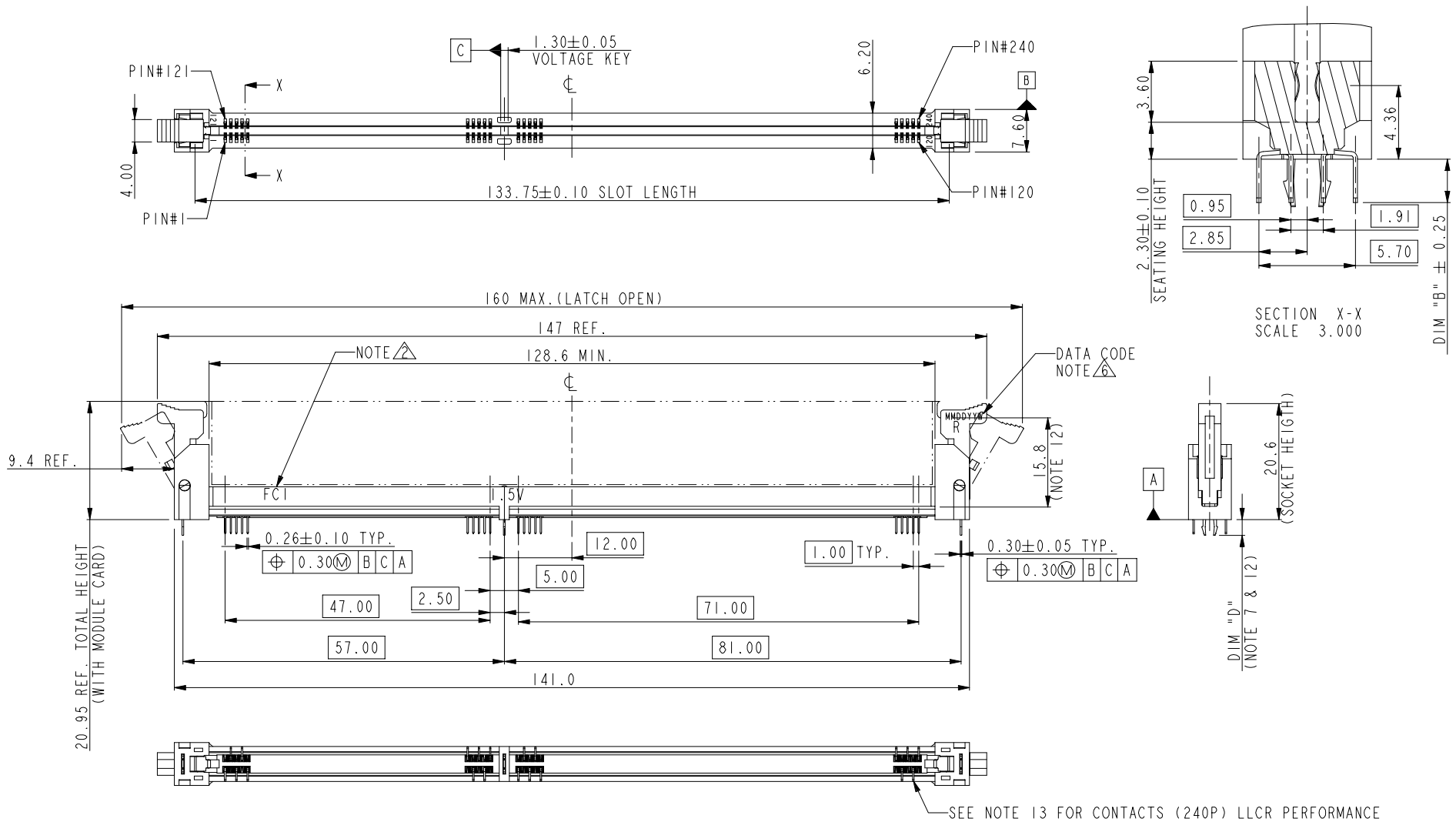




Copyright FCI.



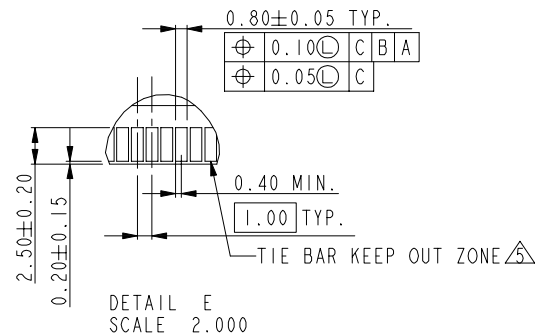
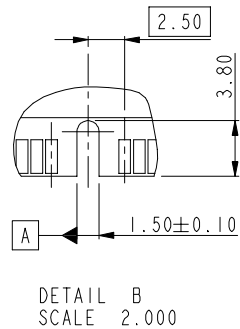
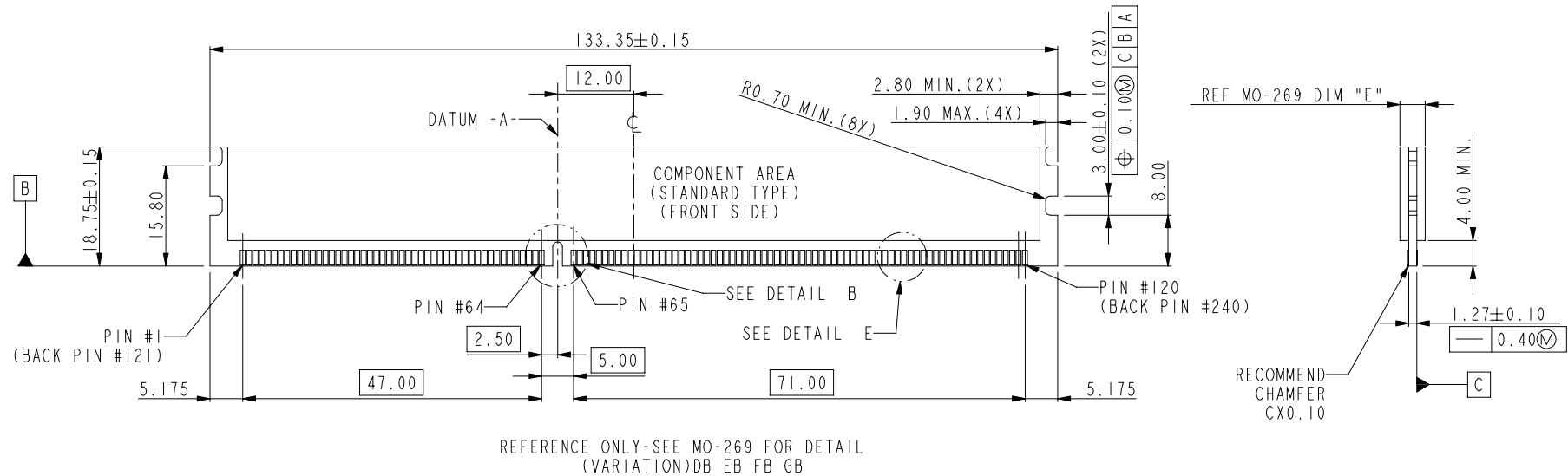
REV F - 2006-04-17

rev	ecn no	dr	date
H	T10-0047	R C	03/24/2010
J	ELX-DG-18042-1	ST	05/27/2014
K	ELX-DG-20235	ST	02/10/2015
-	-	-	-
-	-	-	-
-	-	-	-

www.fciconnect.com				surface - 		tolerance std							
				TOLERANCES UNLESS OTHERWISE SPECIFIED									
Dr	STONE	LI	02/10/2015	ANGULAR	LINEAR	0.X	±0.38	size	A4	Scale	0.707		
Eng	STONE	LI	02/10/2015			0.XX	±0.25						
Chr	ARAY ZHANG	02/10/2015	0° ±5°			0.XXX	±0.13						
Appr	Collins Lu	02/10/2015	Product family				-	ECN / Spec ref *					
			title				VERY LOW PROFILE(VLP) T.H				dwg no	10079192	Rev. K
			DDR3, 240P SOCKET(FOR RDIMM MOUDLE)										
			catalog no				-						
							CUSTOMER				sheet 1 of 4		



Copyright FCI.



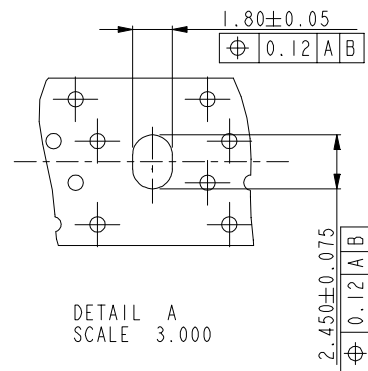
www.fciconnect.com				surface - ✓		tolerance std		projection 		MM 		
				TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	STONE	LI	02/10/2015	ANGULAR LINEAR		0.X		±0.38		size A4	Scale 1.000	
Eng	STONE	LI	02/10/2015			0.XX		±0.25				
Chr	ARAY	ZHANG	02/10/2015	0° ±5°		0.XXX		±0.13		ECN /		
Appr	Collins	Lu	02/10/2015	Product family				-		Spec ref *		
		title	VERY LOW PROFILE (VLP) T.H						dwg no 10079192		Rev. K	
			DDR3, 240P SOCKET (FOR RDIMM MODULE)									
			catalog no -						CUSTOMER			sheet 2 of 4



Copyright FCI.

REV F - 2006-04-17

RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



www.fciconnect.com				surface - ✓		tolerance std		projection 		MM 				
				TOLERANCES UNLESS OTHERWISE SPECIFIED										
Dr	STONE	LI	02/10/2015	ANGULAR	LINEAR	0.X		±0.38		size	A4	Scale	0.707	
Eng	STONE	LI	02/10/2015			0.XX		±0.25						
Chr	ARAY	ZHANG	02/10/2015	0°	±5°	0.XXX		±0.13		ECN			/	
Appr	Collins	Lu	02/10/2015	Product family				-		Spec ref				*
		title	VERY LOW PROFILE(VLP) T.H						dwg no		10079192		Rev.	K
			DDR3, 240P SOCKET(FOR RDIMM MOUDLE)											
			catalog no			-			CUSTOMER			sheet 3 of 4		

10079192 - □ □ □ □

STYLE : MECHANICAL KEYING

I : 1.5 VOLT. W/ CENTER KEY

PLATING

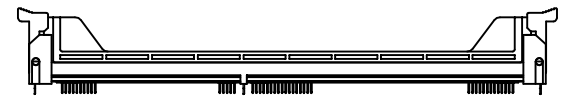
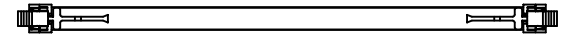
CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2LF	15u" (0.38um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27um) MIN. NICKEL OVERALL
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

CONTACT & FORKLICK LENGTH

CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 mm (0.063")
11	3.18 mm	4.00 mm	2.36 mm (0.093")

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
1 : BLACK HOUSING + AMBER EJECTOR (NOTE. 11)
2 : BLACK HOUSING + BLACK EJECTOR
8 : IVORY HOUSING + IVORY EJECTOR
9 : IVORY HOUSING + BLACK EJECTOR
3 : BLUE HOUSING + IVORY EJECTOR
△K4 : BLACK HOUSING + IVORY EJECTOR + CAP



PRODUCT WITH CAP ILLUSTRATION

NOTES:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
TERMINAL: HIGH PERFORMANCE COPPER ALLOY
METAL CLIP: COPPER ALLOY.
2. FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.
3. PRODUCT SPECIFICATION: GS-12-486.
4. PACKAGING SPECIFICATION: GS-14-899.
5. FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.
6. THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE. "R" MEANS FOR 'RDIMM' SOCKET.
7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.
8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X. (SUSPENDED BY JEDEC)
9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
10. THE HOUSING WILL WITH STAND EXPOSURE TO $260 \pm 5^{\circ}\text{C}$ PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.
11. AMBER EJECTOR OPTION IS ONLY FOR SOLDERING ENVIRONMENT TEMP. UNDER 170°C .
12. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.
13. THIS SOCKET CONTACT EOL RESISTANCE IS DESIGNED TO BE 20 mohm MAX.



Copyright FCI.

www.fciconnect.com				surface - ✓		tolerance std		projection 		MM 					
				TOLERANCES UNLESS OTHERWISE SPECIFIED											
Dr	STONE	LI	02/10/2015	ANGULAR LINEAR		0.X		±0.38		size	A4	Scale	1.000		
Eng	STONE	LI	02/10/2015			0.XX		±0.25							
Chr	ARAY	ZHANG	02/10/2015	0° ±5°		0.XXX		±0.13		ECN			/		
Appr	Collins	Lu	02/10/2015	Product family				-		Spec ref				*	
		title	VERY LOW PROFILE (VLP) T.H						dwg no			10079192		Rev.	K
			DDR3, 240P SOCKET(FOR RDIMM MOUDLE)												
			catalog no			-			CUSTOMER			sheet 4 of 4			